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ABSTRACT

APPARATUS AND METHOD FOR ENCAPSULATING PRODUCTS

Apparatus for encapsulating products, for instance encapsulating lead frames with epoxy resin, wherein the apparatus comprises:

- one or more pressing devices for encapsulating the products at increased pressure and/or temperature;
- a first carriage device for transferring the products from supply means to the pressing device; and
- a second carriage device for discharging the encapsulated products from the pressing device to discharge means,

wherein the first and second carriage are guidable along collective guide means.

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